B2714 BOARD SPECIFICATIONS

1. Board Layers: 8
2. Layer Stack Order:
   - Layer1 (Artwork_1): Top component layer (Signal_1), 0.5 oz, \( Z(\text{diff}) = 100 \) ohm
   - Layer2 (Artwork_2): Power_1 (GROUND), 1 oz
   - Layer4 (Artwork_4): Inner SIGNAL_3, 0.5 oz, \( Z(\text{single end}) = 50 \) ohm
   - Layer5 (Artwork_5): Power_5/Power_6 (VCCINT1V2/VCCDPLL1V2), 1 oz
   - Layer6 (Artwork_6): Inner SIGNAL_4, 0.5 oz, \( Z(\text{single end}) = 50 \) ohm
   - Layer7 (Artwork_7): Power_7/Power_8/Power_9 (P3V3/P2V5/P1V2), 1 oz
   - Layer8 (Artwork_8): Bottom component layer (signal_2), 0.5 oz, \( Z(\text{diff}) = 100 \) ohm

3. Apply silk screen on both sides:
   - Artwork_9: Top silk screen
   - Artwork_10: Bottom silk screen

4. Apply solder mask over bare copper on both sides:
   - Artwork_11: Top solder mask
   - Artwork_12: Bottom solder mask

5. Material: FR4
6. Board thickness: 0.062" +/- 0.010.
7. Suggested layer thickness specification for impedance verification
8. Copper thickness 1 oz before plating for all the power planes.
9. Copper thickness 0.5 oz before plating for all the signal layers.
10. Immersion Ni/Au finish over bare copper

11. Differential pairs: trace/gap/trace=5/5/5 mils
12. All differential pairs impedance \( Z(\text{diff}) \) controlled at 100 ohm (+/-10%)
13. All other traces, minimum clearance = 5 mils
14. All dimensions are in inches unless otherwise noted.

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B2714 specifications

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SPC# B2714
ASM# B2715

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DRAWN TANG
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